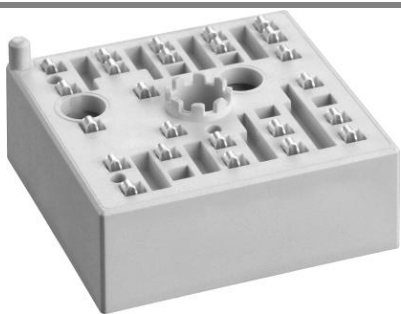


SKiiP 16GH066V1



MiniSKiiP®1

H-bridge inverter

SKiiP 16GH066V1

Preliminary Data

Features

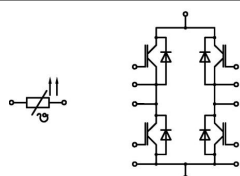
- Trench IGBTs
- Robust and soft freewheeling diode in CAL technology
- Highly reliable spring contacts for electrical connection
- UL recognised file no. E63532

Remarks

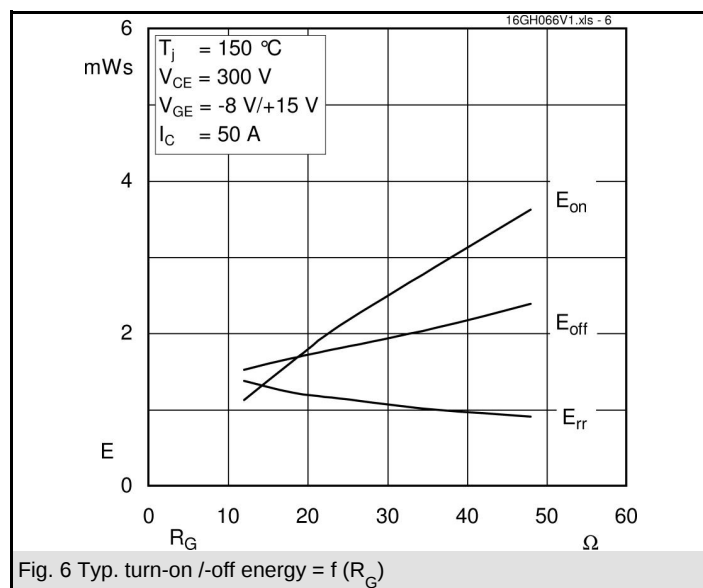
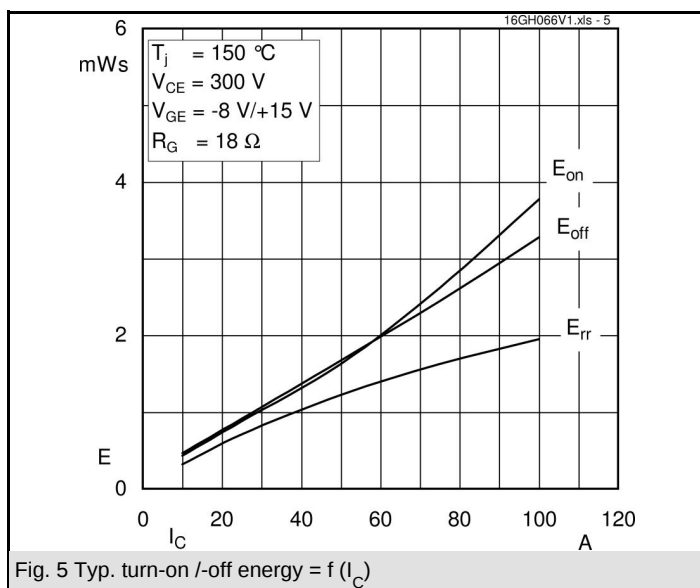
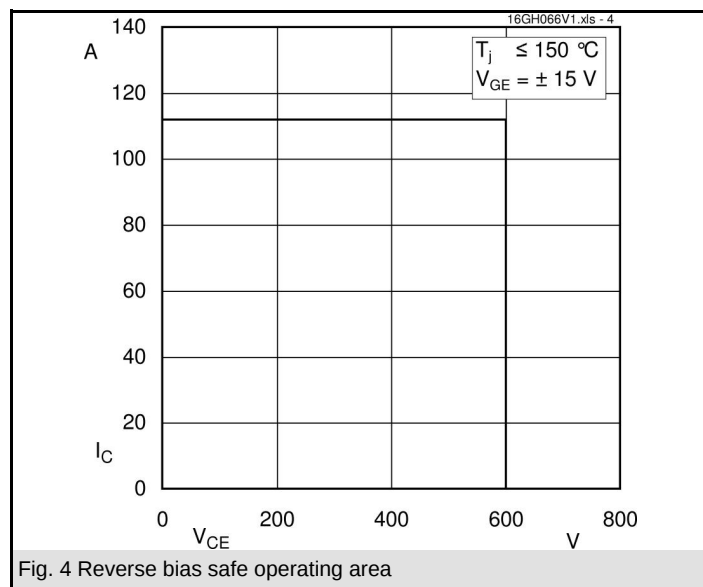
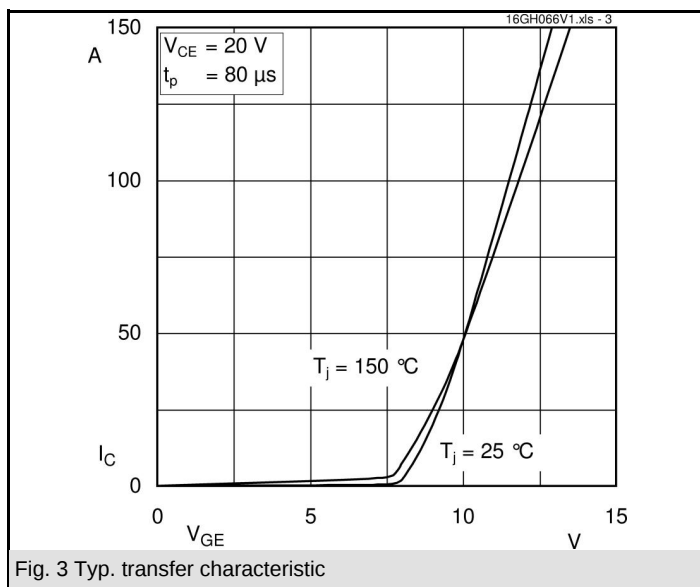
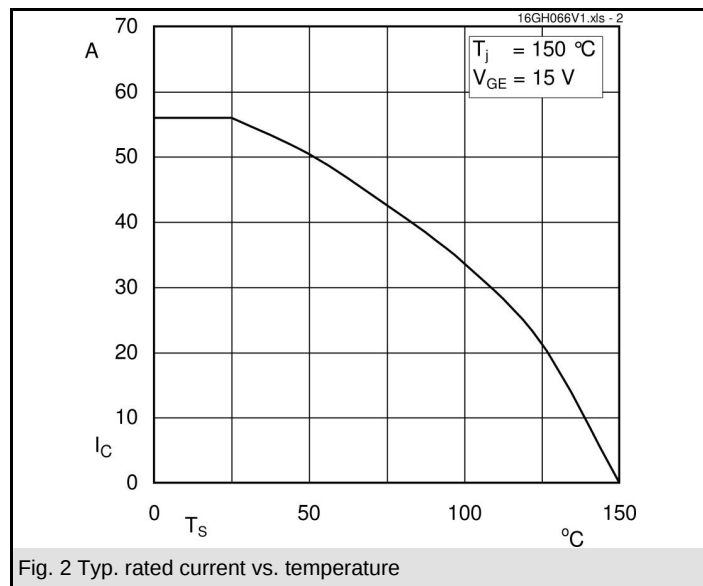
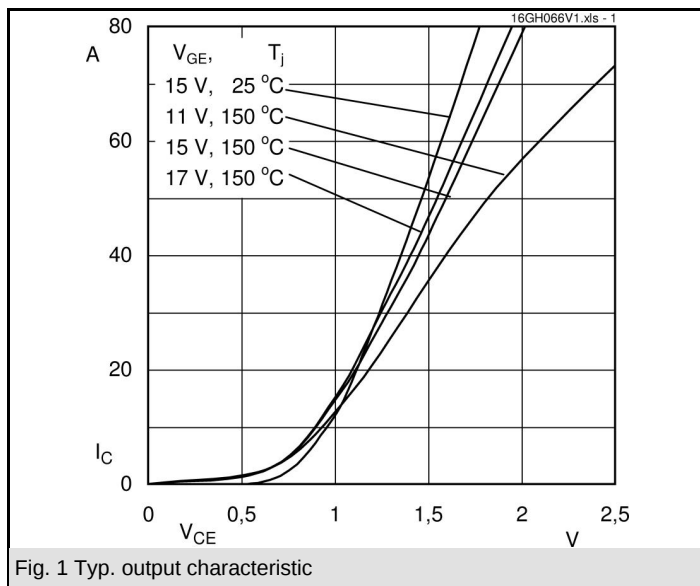
- Case temperature limited to $T_C = 125^\circ\text{C}$
- Product reliability results are valid for $T_j = 150^\circ\text{C}$
- SC data: $t_p \leq 6 \mu\text{s}$; $V_{GE} \leq 15 \text{ V}$; $T_j = 150^\circ\text{C}$; $V_{CC} = 360 \text{ V}$
- V_{CEsat} , V_F = chip level value

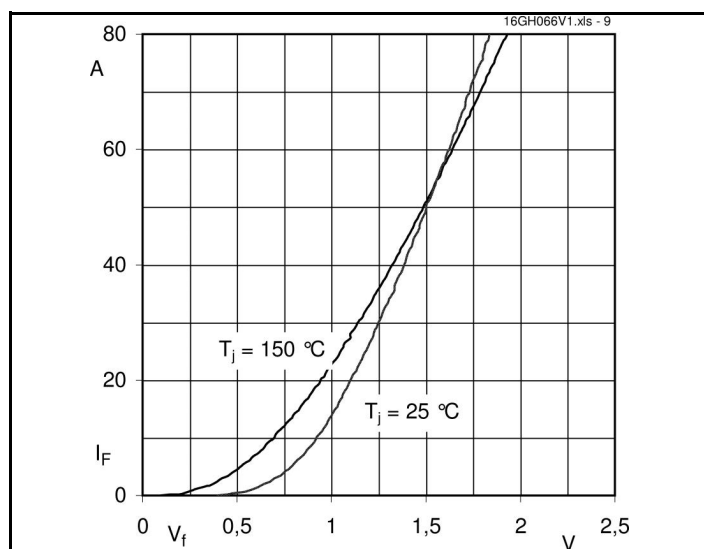
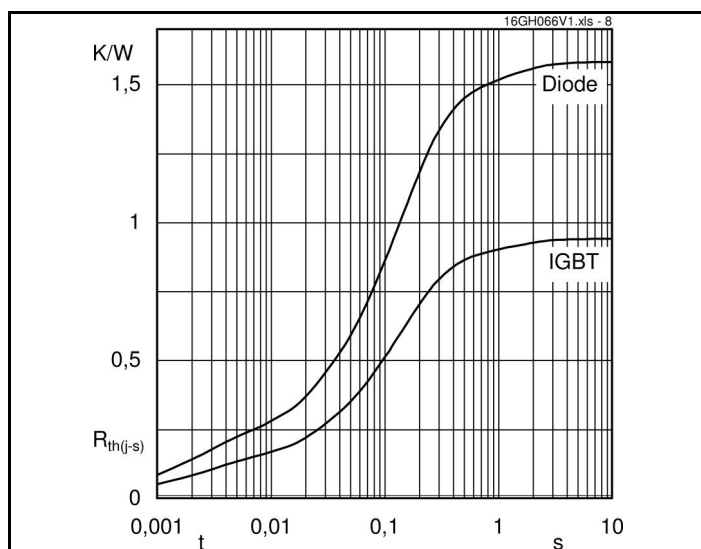
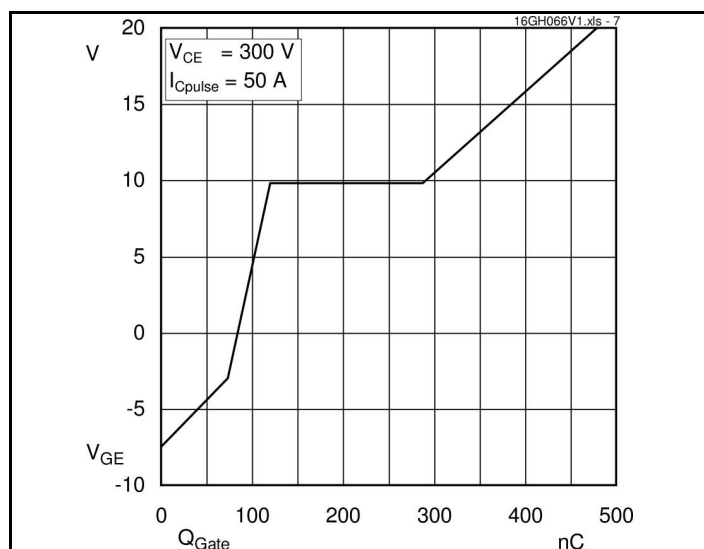
Absolute Maximum Ratings		$T_S = 25^\circ\text{C}$, unless otherwise specified	
Symbol	Conditions	Values	Units
IGBT - Inverter			
V_{CES}		600	V
I_C	$T_S = 25 (70)^\circ\text{C}$, $T_j = 150^\circ\text{C}$	56 (43)	A
I_C	$T_S = 25 (70)^\circ\text{C}$, $T_j = 175^\circ\text{C}$	61 (49)	A
V_{GES}		± 20	V
T_j		$-40 \dots +175$	$^\circ\text{C}$
Diode - Inverter			
I_F	$T_S = 25 (70)^\circ\text{C}$, $T_j = 150^\circ\text{C}$	48 (35)	A
I_F	$T_S = 25 (70)^\circ\text{C}$, $T_j = 175^\circ\text{C}$	54 (42)	A
T_j		$-40 \dots +175$	$^\circ\text{C}$
I_{tRMS}	per power terminal (20 A / spring)	60	A
T_{stg}	$T_{op} \leq T_{stg}$	$-40 \dots +125$	$^\circ\text{C}$
V_{isol}	AC, 1 min.	2500	V

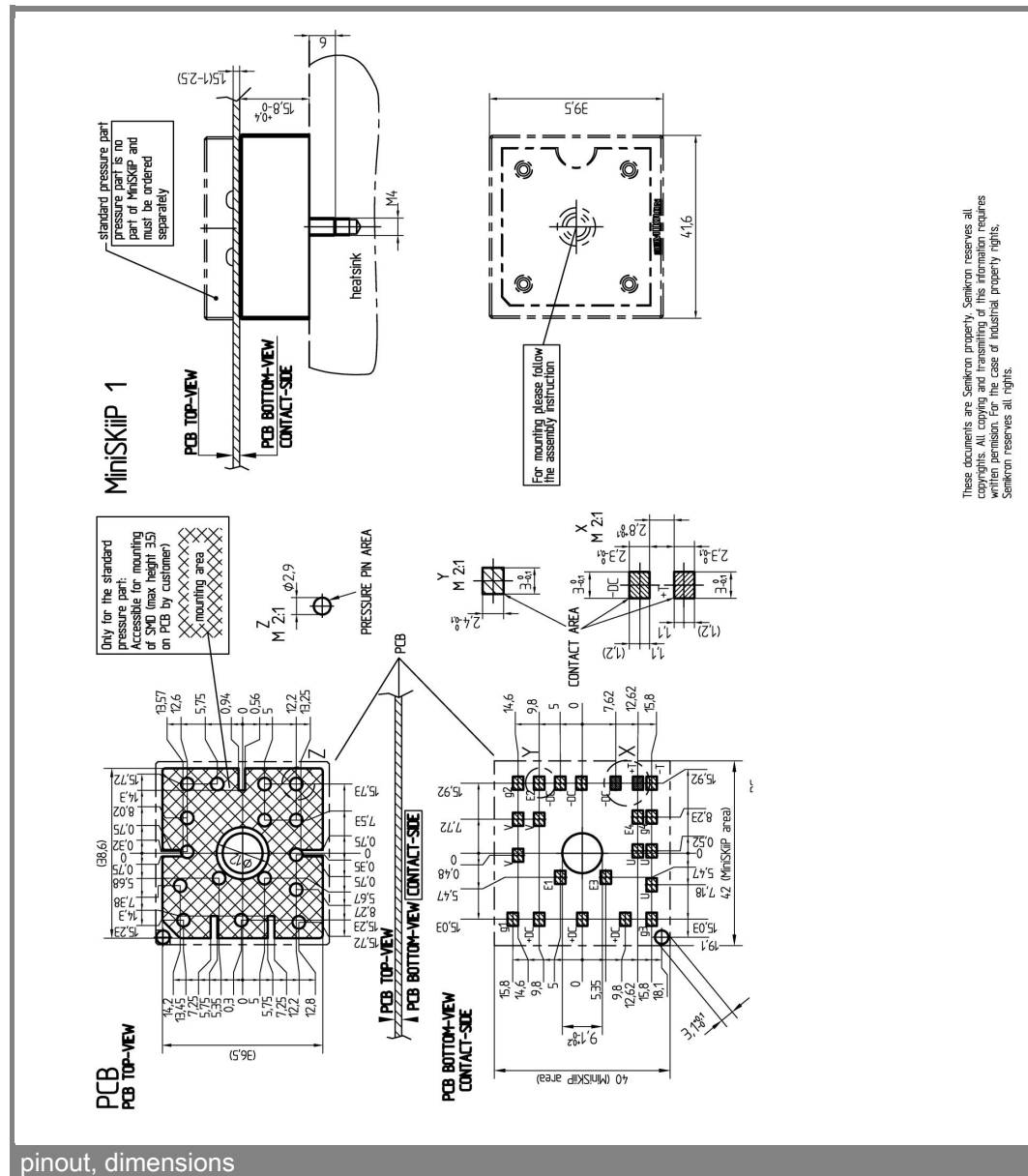
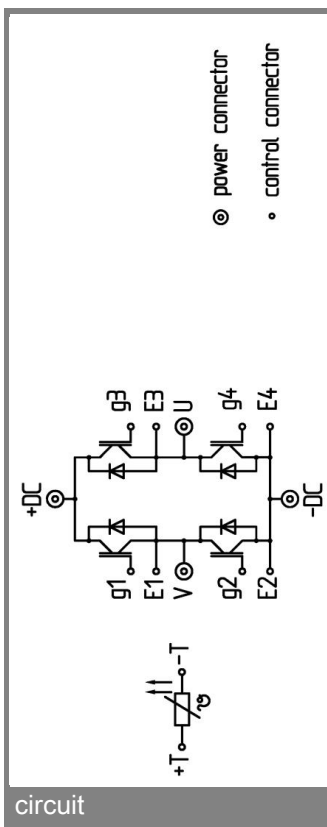
Characteristics		$T_S = 25^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT - Inverter					
V_{CEsat}	$I_C = 50 \text{ A}$, $T_j = 25 (150)^\circ\text{C}$	1,05	1,45 (1,65)	1,85 (2,05)	V
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 1 \text{ mA}$		5,8		V
$V_{CE(TO)}$	$T_j = 25 (150)^\circ\text{C}$		0,9 (0,8)	1,1 (1)	V
r_T	$T_j = 25 (150)^\circ\text{C}$		11 (17)	15 (21)	m Ω
C_{ies}	$V_{CE} = 25 \text{ V}$, $V_{GE} = 0 \text{ V}$, $f = 1 \text{ MHz}$		2,87		nF
C_{oes}	$V_{CE} = 25 \text{ V}$, $V_{GE} = 0 \text{ V}$, $f = 1 \text{ MHz}$		0,6		nF
C_{res}	$V_{CE} = 25 \text{ V}$, $V_{GE} = 0 \text{ V}$, $f = 1 \text{ MHz}$		0,46		nF
$R_{CC+EE'}$	spring contact-chip $T_s = 25 (150)^\circ\text{C}$				m Ω
$R_{th(j-s)}$	per IGBT		0,94		K/W
$t_{d(on)}$	under following conditions		40		ns
t_r	$V_{CC} = 300 \text{ V}$, $V_{GE} = -8\text{V}/+15\text{V}$		40		ns
$t_{d(off)}$	$I_C = 50 \text{ A}$, $T_j = 150^\circ\text{C}$		425		ns
t_f	$R_{Gon} = R_{Goff} = 18 \Omega$		40		ns
$E_{on}(E_{off})$	inductive load		1,65 (1,7)		mJ
Diode - Inverter					
$V_F = V_{EC}$	$I_F = 50 \text{ A}$, $T_j = 25 (150)^\circ\text{C}$		1,5 (1,5)	1,7 (1,7)	V
$V_{(TO)}$	$T_j = 25 (150)^\circ\text{C}$		1 (0,9)	1,1 (1)	V
r_T	$T_j = 25 (150)^\circ\text{C}$		10 (12)	12 (14)	m Ω
$R_{th(j-s)}$	per diode		1,58		K/W
I_{RRM}	under following conditions		44		A
Q_{rr}	$I_F = 50 \text{ A}$, $V_R = 300 \text{ V}$		5,5		μC
E_{rr}	$V_{GE} = 0 \text{ V}$, $T_j = 150^\circ\text{C}$ $di_F/dt = 1400 \text{ A}/\mu\text{s}$		1,25		mJ
Temperature Sensor					
R_{ts}	3 %, $T_r = 25 (100)^\circ\text{C}$		1000(1670)		Ω
Mechanical Data					
m			35		g
M_s	Mounting torque	2		2,5	Nm



GH







This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.